



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130322000
Qualification of CAR as an Additional Assembly Site
for Select Devices in the SSOP (DB) Package
Change Notification / Sample Request

Date: 3/25/2013
To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659




20130322000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DAC7631EB	null
DAC7613E	null
DAC7631E	null
DAC7731E	null
DAC7621E	null
DAC7731EC	null
DAC7614EB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130322000		PCN Date:	03/25/2013	
Title:	Qualification of CAR as an Additional Assembly Site for Select Devices in the SSOP (DB) Package				
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept: Quality Services	
Proposed 1st Ship Date:	06/25/2013	Estimated Sample Availability:	Date provided at sample request		
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Qualification of CAR as an Additional Assembly Site for Select Devices in the SSOP (DB) Package which are currently assembled at CRS.					
Reason for Change:					
Continuity of supply.					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None.					
Changes to product identification resulting from this PCN:					
Sample Product Shipping Label (not actual product label)					
Assembly Site					
CRS		Assembly Site Origin (22L)		ASO: CRS	
CAR		Assembly Site Origin (22L)		ASO: CAR	
  					
MADE IN: Malaysia 2DC: 2Q:					
MSL 2 / 260C / 1 YEAR		SEAL DT			
MSL 1 / 235C / UNLIM		03/29/04			
OPT: ITEM: 39					
LBL: 5A (L) T0:1750					
(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS					

Product Affected:

DAC7613E	DAC7615E	DAC7617E	DAC7631E
DAC7613EB	DAC7615EB	DAC7617EB	DAC7631EB
DAC7613EBG4	DAC7615EBG4	DAC7617EBG4	DAC7631EBG4
DAC7613EG4	DAC7615EG4	DAC7617EG4	DAC7631EG4
DAC7614E	DAC7616E	DAC7621E	DAC7731E
DAC7614EB	DAC7616EB	DAC7621EB	DAC7731EC
DAC7614EBG4	DAC7616EBG4	DAC7621EBG4	DAC7731ECG4
DAC7614EG4	DAC7616EG4	DAC7621EG4	DAC7731EG4

DB Qualification Data: Approved 3/21/2013

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Device 1 : ADS1213E (MSL 2-260C)**Package Construction Details**

Assembly Site:	CAR	Mold Compound:	438360
# Pins-Designator, Family:	28-DB, SSOP	Mount Compound:	434165
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size Pass/Fail
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0
Manufacturability	(Assembly Site)	Pass
Moisture Sensitivity, L2	85C/60%RH/168 Hrs	12/0

Notes: ** Preconditioning sequence Level 2-260C

Qual Device 2 : ADS7871IDB (MSL 2-260C)**Package Construction Details**

Assembly Site:	CAR	Mold Compound:	438358
# Pins-Designator, Family:	28-DB, SSOP	Mount Compound:	434165
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size/Fail
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0
Manufacturability	(Assembly Site)	Pass
Moisture Sensitivity, L2	85C/60%RH/168 Hrs	12/0

Notes: ** Preconditioning sequence Level 2-260C

Qual Device 3 : ADS825E (MSL 2-260C)**Package Construction Details**

Assembly Site:	CAR	Mold Compound:	438360
# Pins-Designator, Family:	28-DB, SSOP	Mount Compound:	434165
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fail		
Solderability	Pb-Free/Solder	22/0		
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0		
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0		
Manufacturability	(Assembly Site)	Pass		
Physical Dimensions	Mechanical drawing	5/0		
Moisture Sensitivity, L2	85C/60%RH/168 Hrs	12/0		
Notes: ** Preconditioning sequence Level 2-260C				
Qual Device 4 : DAC8820IBDB (MSL 2-260C)				
Package Construction Details				
Assembly Site:	CAR	Mold Compound:	438518	
# Pins-Designator, Family:	28-DB, SSOP	Mount Compound:	434165	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fail		
		Lot 1	Lot 2	Lot 3
Manufacturability	(Assembly Site)	Pass	Pass	Pass
Solderability	8 Hrs/Stm Age, Pb-Free/Solder	22/0	22/0	-
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Physical Dimensions	Mechanical drawing	5/0	-	-
Moisture Sensitivity, L2	85C/60%RH/168 Hrs	12/0	12/0	-
Notes: ** Preconditioning sequence Level 2-260C				
Qual Device 5 : PGA2505IDB (MSL 2-260C)				
Package Construction Details				
Assembly Site:	CAR	Mold Compound:	438360	
# Pins-Designator, Family:	24-DB, SSOP	Mount Compound:	434165	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fail		
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0		
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0		
Manufacturability	(Assembly Site)	Pass		
Physical Dimensions	Mechanical drawing	5/0		
Moisture Sensitivity, L2	85C/60%RH/168 Hrs	12/0		
Notes: ** Preconditioning sequence Level 2-260C				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com